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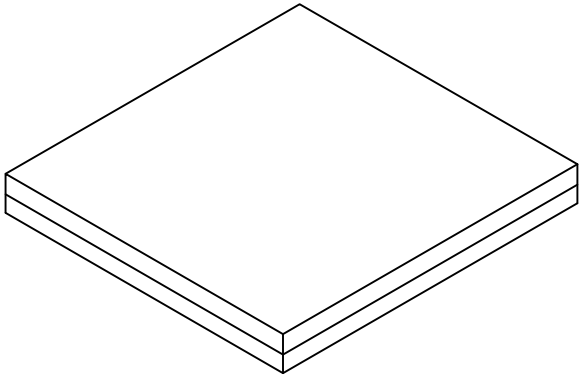
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C05457	04/06/99	E.B.	L.J.M.



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 169.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL	ANGULAR
X.X ±0.10	±1°
X.XX ±0.05	
X.XXX ±0.03	

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	L. MACKEY	03/17/99
CHECKED	J. MICKSCH	03/17/99
ENG'R	T. PANCZAK	03/17/99
RELEASED	G. SCHULTZ	04/06/99

ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea

AMKOR Electronics, Inc. Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CABGA 192, 14.00mm X 14.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	74750	00

STRIP DWG NUMBER/REV	CUST CODE	SCALE	SHEET
N/A	N/A	SCALE: 8:1	SHEET 1 OF 3

ZF00004 REV E